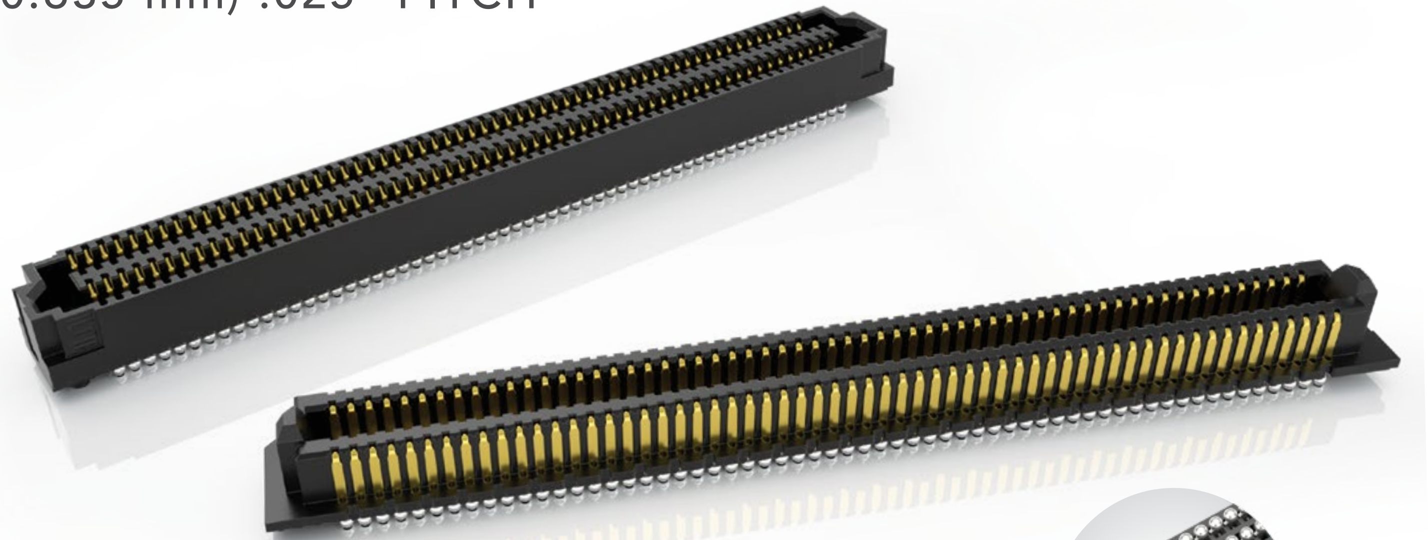
ACCELERATE® HD

HIGH-DENSITY SLIM BODY ARRAYS

(0.635 mm) .025" PITCH



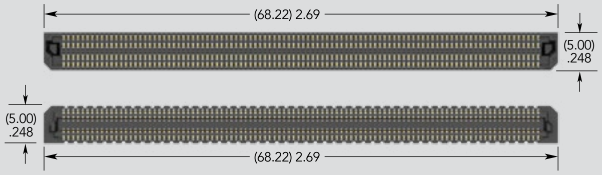
PAM4
56 Gbps

Solder ball technology
for simplified processing

FEATURES & BENEFITS

- Up to 240 positions in 4-row design (400 positions in development)
- Low-profile 5 mm stack heights
- Slim 5 mm width body design
- Edge Rate® contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- PCIe® 5.0 capable
- Compatible with mPower® (UMPT/UMPS) for a power signal solution

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS



ADM6/ADF6 Series (400 total positions)

KEY SPECIFICATIONS

PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 240	Black LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	-55 °C to +125 °C	1.34 A per pin (4 pins powered)	Testing now	Yes

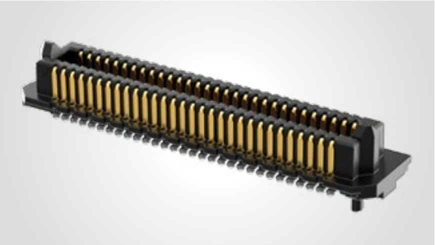
(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS

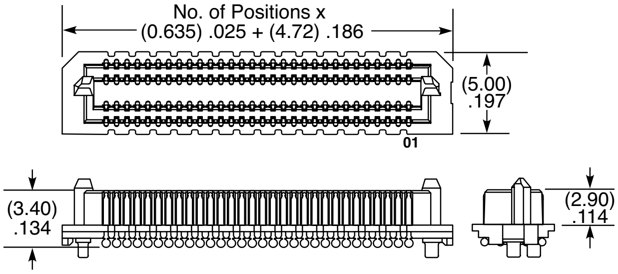
SERIES	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X" R
ADM6 Terminal **ADF6** Socket	**–10, –20, –30, –40, –50, –60** (per row)	**–01.5** = 1.5 mm (ADM6 only) **–03.5** = 3.5 mm (ADF6 only)	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on tail	**–4** = Four Rows	**–2** = Lead-Free Solder Ball	(Leave blank for no alignment pin) **–A** = Alignment Pin	**–TR** = Tape & Reel **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

ADM6

Board Mates:
ADF6

Standoffs:
JSO





View complete specifications at: samtec.com?ADM6

MATED HEIGHTS *

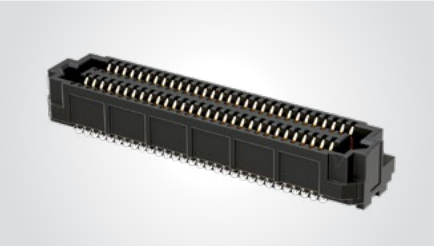
ADF6 LEAD STYLE	ADM6 LEAD STYLE
	-01.5
-03.5	(5 mm) .197"

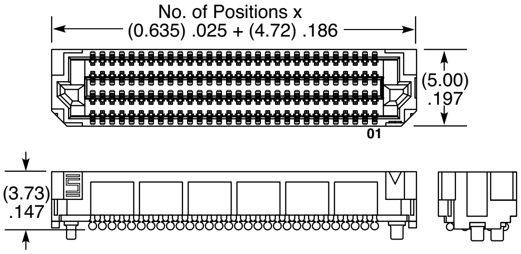
* Processing conditions will affect mated height.

ADF6

Board Mates:
ADM6

Standoffs:
JSO





Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6